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- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Typical V<sub>OLP</sub> (Output Ground Bounce) < 1 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C
- High-Drive Outputs (-32-mA I<sub>OH</sub>, 64-mA I<sub>OL</sub>)
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs

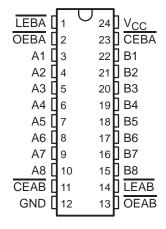
#### description

The 'ABT543A octal transceivers contain two sets of D-type latches for temporary storage of data flowing in either direction. Separate latch-enable (LEAB or LEBA) and output-enable (OEAB or OEBA) inputs are provided for each register to permit independent control in either direction of data flow.

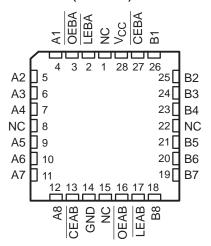
The A-to-B enable  $(\overline{CEAB})$  input must be <u>low to</u> enter data from A or to output data from B. If  $\overline{CEAB}$  is low and  $\overline{LEAB}$  is low, the A-to-B latches are transparent; a subsequent low-to-high transition of  $\overline{LEAB}$  puts the A latches in the storage mode. With  $\overline{CEAB}$  and  $\overline{OEAB}$  both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is <u>similar</u>, but requires using the  $\overline{CEBA}$ ,  $\overline{LEBA}$ , and  $\overline{OEBA}$  inputs.

To ensure the high-impedance state during power up or power down,  $\overline{\text{OE}}$  should be tied to  $V_{\text{CC}}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

SN54ABT543A . . . JT OR W PACKAGE SN74ABT543A . . . DB, DW, NT, OR PW PACKAGE (TOP VIEW)



# SN54ABT543A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

The SN54ABT543A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT543A is characterized for operation from –40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-IIB is a trademark of Texas Instruments Incorporated.



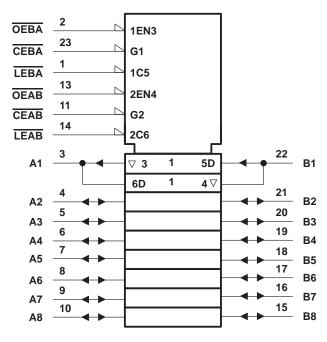
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#### **FUNCTION TABLE**†

	INPUTS									
CEAB	LEAB	OEAB	В							
Н	Х	Х	Χ	Z						
Х	X	Н	Χ	Z						
L	Н	L	Χ	в <sub>0</sub> ‡						
L	L	L	L	L						
L	L	L	Н	Н						

<sup>†</sup> A-to-B data flow is shown; B-to-A flow control is the same except that it uses CEBA, LEBA, and OEBA.

## logic symbol§



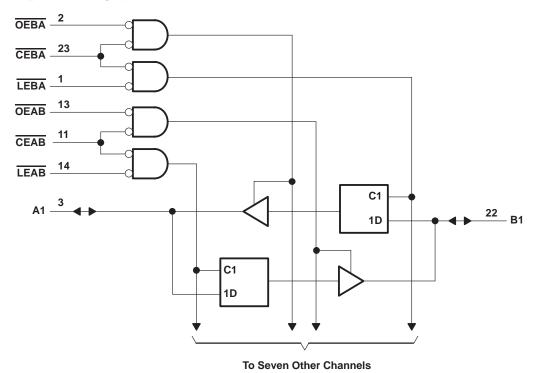
§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.



<sup>‡</sup>Output level before the indicated steady-state input conditions were established

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#### logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	$\dots$ -0.5 V to 7 V
Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, Vo	0.5 V to 5.5 V
Current into any output in the low state, Io: SN54ABT543A	96 mA
SN74ABT543A	128 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–18 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ )	
Package thermal impedance, θ <sub>.IA</sub> (see Note 2): DB package	
DW package	
NT package	67°C/W
PW package	120°C/W
Storage temperature range, T <sub>stg</sub>	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.



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#### recommended operating conditions (see Note 3)

			SN54AB	T543A	SN74AB	T543A	UNIT
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2		2		V
VIL	Low-level input voltage			0.8		0.8	V
٧ <sub>I</sub>	Input voltage		0	Vcc	0	VCC	V
IOH	High-level output current			-24		-32	mA
IOL	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
TA	Operating free-air temperature		<del>-</del> 55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			NETIONS	Т	A = 25°C	;	SN54AB	T543A	SN74AB	T543A	
PAI	RAMETER	l lesi co	NDITIONS	MIN	TYP <sup>†</sup>	MAX	MIN	MAX	MIN	MAX	UNIT
VIK		V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
\/		V <sub>CC</sub> = 5 V,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
VOН		V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -24 mA	2			2				V
		vCC = 4.5 v	$I_{OH} = -32 \text{ mA}$	2*					2		
		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 48 mA			0.55		0.55			V
VOL		VCC = 4.5 V	I <sub>OL</sub> = 64 mA			0.55*				0.55	V
V <sub>hys</sub>					100						mV
١.	Control inputs	V00 - 5 5 V	V1 - V20 or CND			±1		±1		±1	
וי	A or B ports $V_{CC} = 5.5 \text{ V},$		$V_I = V_{CC}$ or GND			±100		±100		±100	μΑ
lozH <sup>‡</sup>		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.7 V			10§		10§		10§	μΑ
I <sub>OZL</sub> ‡		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 0.5 V			-10§		-10§		-10§	μΑ
I <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ
ICEX		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 5.5 V	Outputs high			50		50		50	μΑ
IO¶		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.5 V	-50*	-100	-180*	-50	-200	-50	-180	mA
		V <sub>CC</sub> = 5.5 V,	Outputs high		1	250*		350		250	μΑ
Icc	A or B ports	$I_{O} = 0$ ,	Outputs low		24	30*		34		30	mA
		$V_I = V_{CC}$ or GND	Outputs disabled		0.5	250*		350		250	μΑ
Δl <sub>CC</sub> #		V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND				1.5		1.5		1.5	mA
Ci	Control inputs $V_1 = 2.5 \text{ V or } 0.5 \text{ V}$				4						pF
Cio	A or B ports	V <sub>O</sub> = 2.5 V or 0.5 V			7						pF

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter does not apply.



<sup>†</sup> All typical values are at  $V_{CC}$  = 5 V. ‡ The parameters  $I_{OZH}$  and  $I_{OZL}$  include the input leakage current.

<sup>§</sup> This data sheet limit may vary among suppliers.

 $<sup>\</sup>P$  Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

 $<sup>^{\#}</sup>$  This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

					SN54AE	3T543A		
				V <sub>CC</sub> :	= 5 V, 25°C	MIN	MAX	UNIT
				MIN	MAX			
t <sub>W</sub>	Pulse duration, LEAB or LEBA low			3.5		3.5		ns
		Data before LEAB or LEBA↑		2.5		2.5		
<b> </b> .	Setup time	Data belore LEAB or LEBAT	Low	3		3		ns
t <sub>su</sub>	Setup time	Data before CEAB or CEBA↑	High	2.5		2.5		115
		Data before CEAB of CEBAT	Low	3		3		
<b>.</b>	Hold time	Data after LEAB or LEBA↑	·	1		1		nc
th	riola time	Data after CEAB or CEBA↑	·	1		1		ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

					SN74AE	3T543A		
				V <sub>CC</sub> =	= 5 V, 25°C	MIN	MAX	UNIT
				MIN	MAX			
t <sub>W</sub>	Pulse duration, LEAB or LEBA low			3.5		3.5		ns
		Data before <u>LEAB</u> or <u>LEBA</u> ↑	High	3.5		3.5		
۱.	Setup time	Data before LEAD of LEBAT	Low	3		3		ns
t <sub>su</sub>	Setup time	Data before CEAB or CEBA↑	High	3.5		3.5		115
		Data before CEAB of CEBA	Low	3		3		
ļ.,	Hold time	Data after LEAB or LEBA↑	0.5		0.5		ns	
th	riola little	Data after CEAB or CEBA↑	·	0.5		0.5		115



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# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

				SN5	4ABT54	3A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>C</sub>	CC = 5 V A = 25°C	', ;	MIN	MAX	UNIT
			MIN	TYP	MAX			
t <sub>PLH</sub>	A or B	B or A	1.6†	4.4	4.4	1.6†	5.5	ns
t <sub>PHL</sub>	AOIB	BULK	1.6	4.4	5.1	1.6	6.2	115
tPLH	LEBA or LEAB	A or B	1.6†	4.1	5.1	1.6†	6.6	ns
t <sub>PHL</sub>	LEDA OI LEAD	AOID	1.6	4.6	5.4	1.6	6.4	115
<sup>t</sup> PZH	OEBA or OEAB	A or B	1.4	3.9	4.1	1.4	5.1	ns
tPZL	OEBA OF OEAB	AUID	2	5	4.9	2	5.8	115
<sup>t</sup> PHZ	OEBA or OEAB	A or B	2.5†	5.9	5.8	2.5†	6.9	ns
<sup>t</sup> PLZ	OEDA OI OEAD	AOID	2.5†	5.5	6.1	2.5†	7.6	115
<sup>t</sup> PZH	CEBA or CEAB	A or B	1.4	3.9	4.7	1.4	5.6	20
tPZL	CEDA OF CEAB	A UI B	2	5	5.7	2	6.2	ns
<sup>t</sup> PHZ	CEBA or CEAB	A or B	3.2†	5.9	6.5	3.2†	7.3	—l ns I
t <sub>PLZ</sub>	OLDA OI OLAD	AUID	2.5†	5.5	6.7	2.5†	7.8	

<sup>†</sup> This data sheet limit may vary among suppliers.

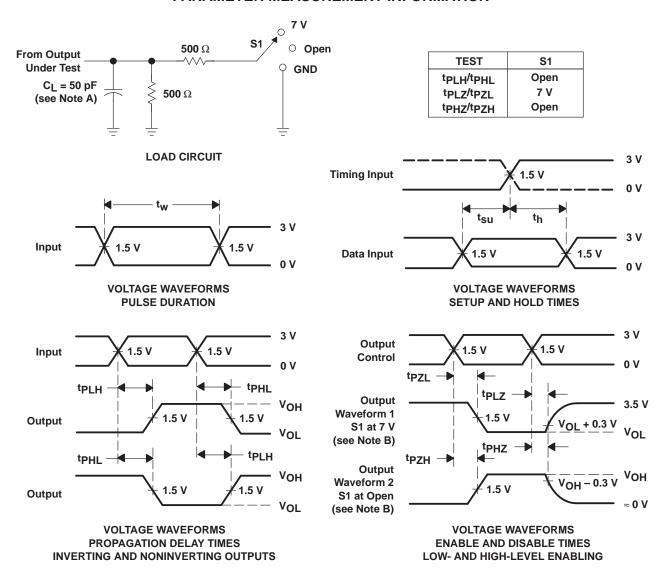
# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

				SN7	4ABT54	3A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)		CC = 5 V 4 = 25°C		MIN	MAX	UNIT
			MIN	TYP	MAX			
<sup>t</sup> PLH	A or B	B or A	1.8†	4.4	5.9	1.8†	6.9	ns
<sup>t</sup> PHL	AOIB	BULK	1.9	4.4	5.9	1.9	6.9	115
tPLH	LEBA or LEAB	A or B	1.5†	4.1	5.6	1.5†	6.6	ns
<sup>t</sup> PHL	LEDA OI LEAD	AOIB	2.1	4.6	6.1	2.1	7.1	115
<sup>t</sup> PZH	OEBA or OEAB	A or B	1.4	3.9	5.4	1.4	6.4	ns
t <sub>PZL</sub>	OEBA OI OEAB	AOID	2.5	5	6.5	2.5	7.5	115
t <sub>PHZ</sub>	OEBA or OEAB	A or B	2.5†	5.9	7.4	2.5†	8.4	ns
t <sub>PLZ</sub>	OEBA OI OEAB	AOIB	2.5†	5.5	7	2.5†	8	115
<sup>t</sup> PZH	CEBA or CEAB	A or B	1.4	3.9	5.4	1.4	6.4	ns
t <sub>PZL</sub>	CEDA OF CEAB	AUID	2.5	5	6.5	2.5	7.5	115
<sup>t</sup> PHZ	CEBA or CEAB	A or B	2.9†	5.9	7.4	2.9†	8.4	—l ns l
<sup>t</sup> PLZ	OLDA OF CLAB	AUIB	2.4†	5.5	7	2.4†	8	

<sup>†</sup>This data sheet limit may vary among suppliers.



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5$  ns,  $t_f \leq 2.5$  ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



## **PACKAGE OPTION ADDENDUM**

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#### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	n MSL Peak Temp <sup>(3)</sup>
5962-9231402Q3A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9231402QKA	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type
5962-9231402QLA	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type
SN74ABT543ADBLE	OBSOLETE	SSOP	DB	24		TBD	Call TI	Call TI
SN74ABT543ADBR	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPD	Level-1-260C-UNLIM
SN74ABT543ADBRE4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPD	Level-1-260C-UNLIM
SN74ABT543ADBRG4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPD	Level-1-260C-UNLIM
SN74ABT543ADW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT543ADWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT543ADWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT543ADWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT543ADWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT543ADWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT543ANSR	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT543ANSRE4	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT543ANSRG4	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT543ANT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ABT543ANTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ABT543APW	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT543APWE4	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT543APWG4	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT543APWLE	OBSOLETE	TSSOP	PW	24		TBD	Call TI	Call TI
SN74ABT543APWR	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT543APWRE4	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT543APWRG4	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ABT543AFK	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54ABT543AJT	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type
SNJ54ABT543AW	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type



#### PACKAGE OPTION ADDENDUM

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(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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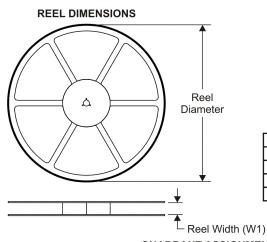
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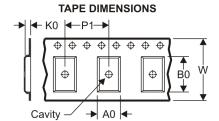




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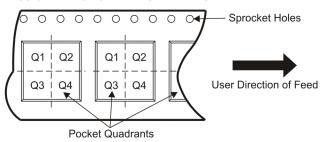
#### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

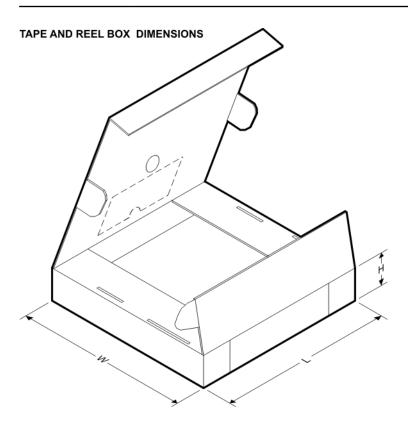


\*All dimensions are nominal

Device	Packaç Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT543ADE	SR SSOF	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
SN74ABT543ADV	VR SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74ABT543ANS	SR SO	NS	24	2000	330.0	24.4	8.2	15.4	2.5	12.0	24.0	Q1
SN74ABT543APV	VR TSSO	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

## PACKAGE MATERIALS INFORMATION

11-Mar-2008



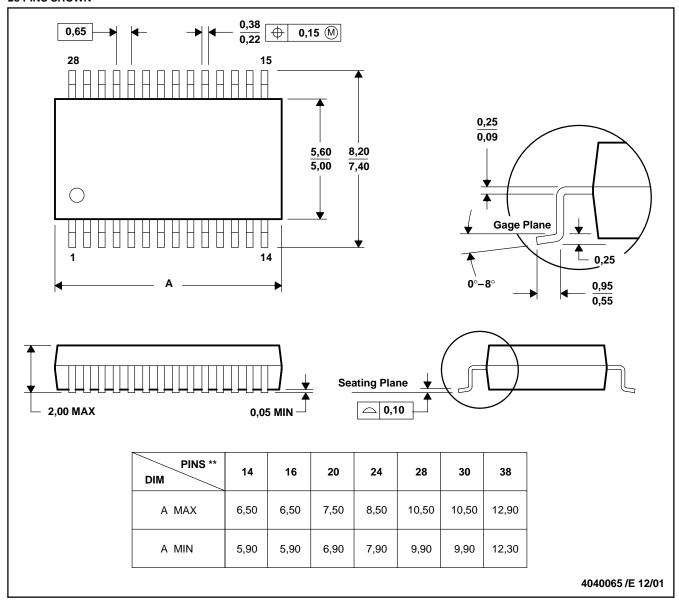
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT543ADBR	SSOP	DB	24	2000	346.0	346.0	33.0
SN74ABT543ADWR	SOIC	DW	24	2000	346.0	346.0	41.0
SN74ABT543ANSR	SO	NS	24	2000	346.0	346.0	41.0
SN74ABT543APWR	TSSOP	PW	24	2000	346.0	346.0	33.0

#### DB (R-PDSO-G\*\*)

#### PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

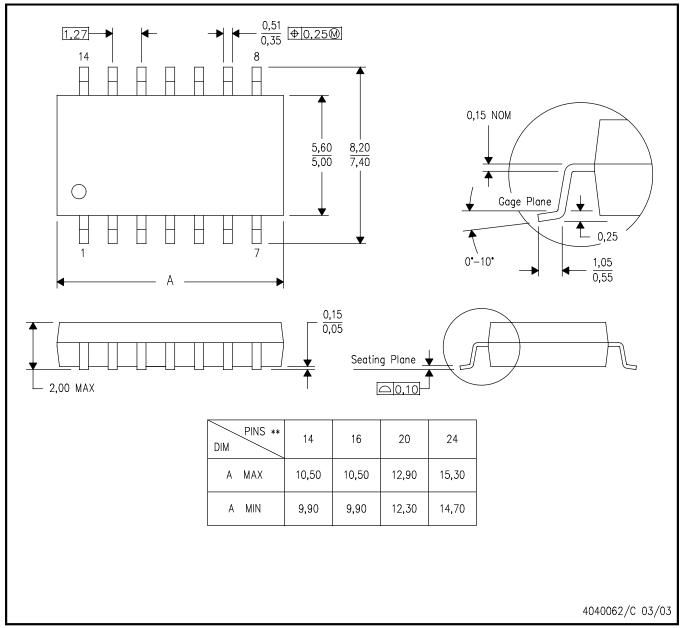
D. Falls within JEDEC MO-150

#### **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

## 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



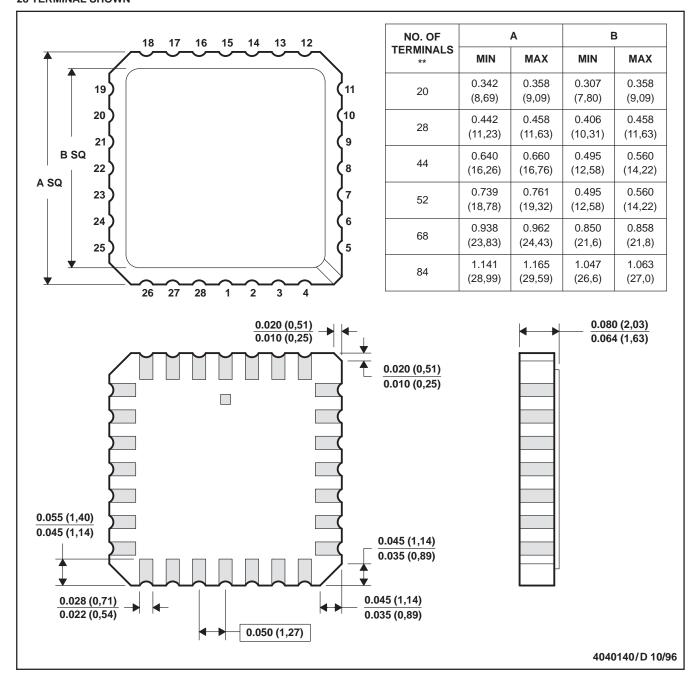
NOTES:

- All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

#### FK (S-CQCC-N\*\*)

#### **28 TERMINAL SHOWN**

#### **LEADLESS CERAMIC CHIP CARRIER**



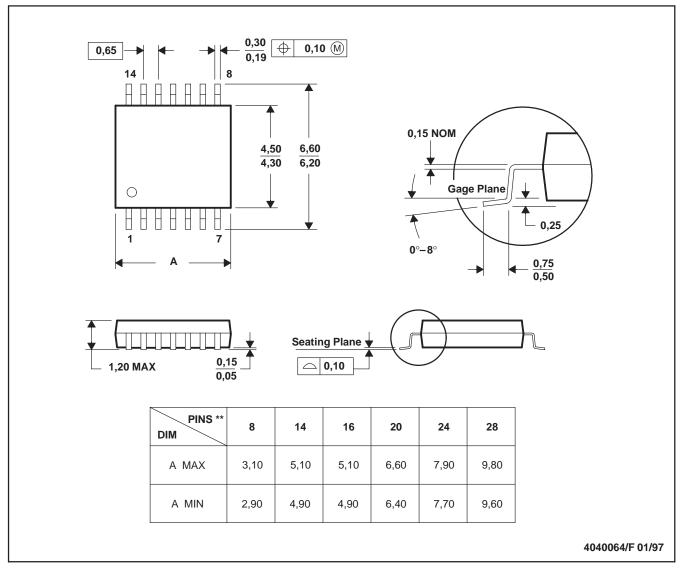
- NOTES: A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004



#### PW (R-PDSO-G\*\*)

#### 14 PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

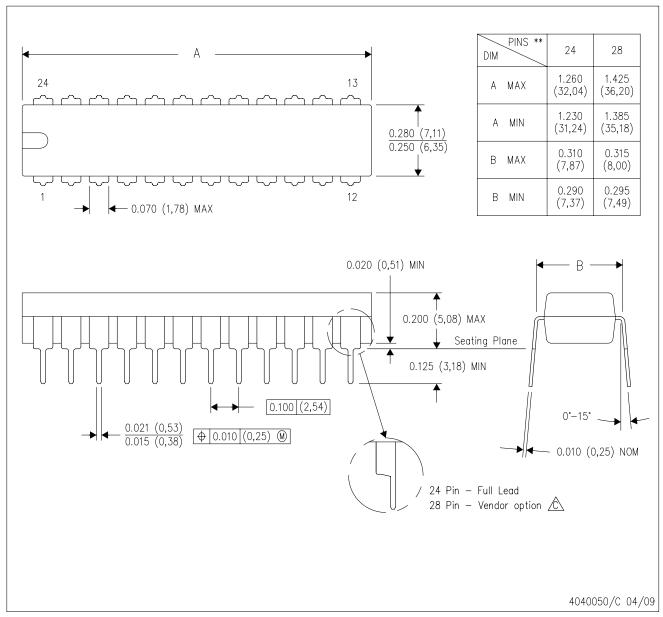
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

NT (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



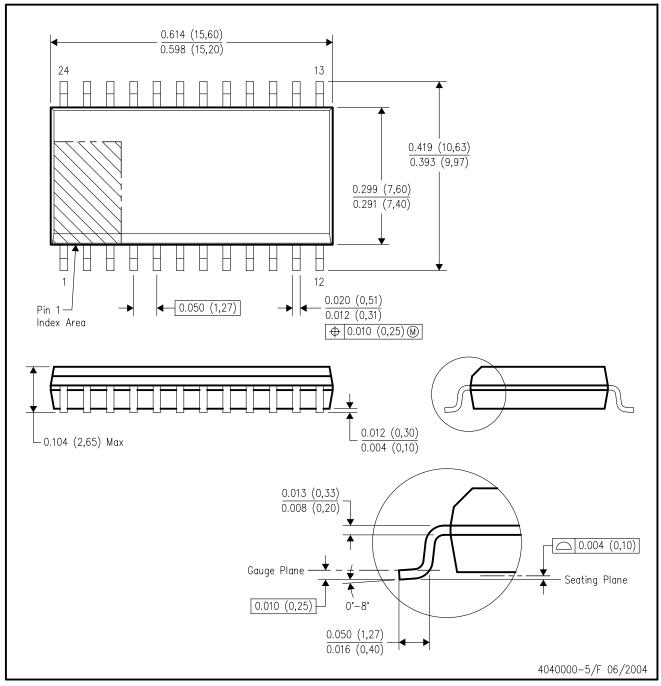
NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

The 28 pin end lead shoulder width is a vendor option, either half or full width.

## DW (R-PDSO-G24)

## PLASTIC SMALL-OUTLINE PACKAGE

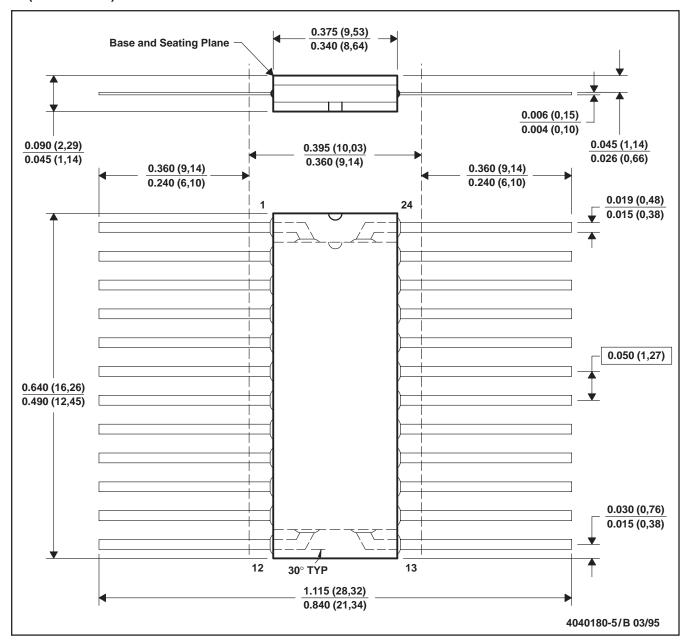


NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.

#### W (R-GDFP-F24)

#### **CERAMIC DUAL FLATPACK**



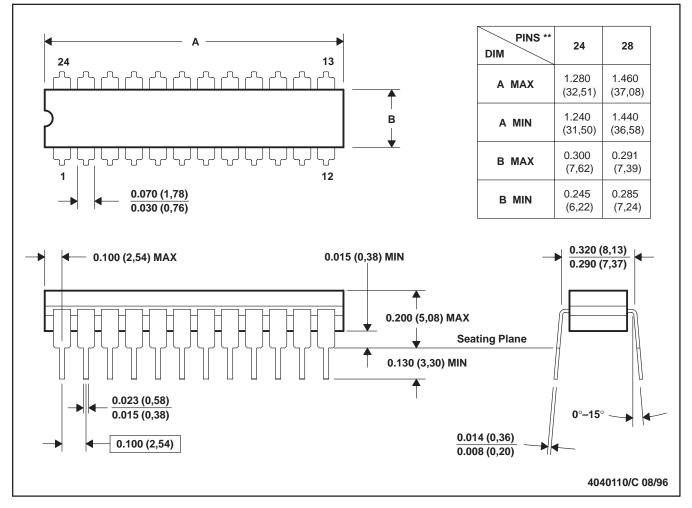
- NOTES: A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Falls within MIL-STD-1835 GDFP2-F24 and JEDEC MO-070AD
  - E. Index point is provided on cap for terminal identification only.



#### JT (R-GDIP-T\*\*)

#### 24 LEADS SHOWN

#### **CERAMIC DUAL-IN-LINE**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

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